



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21F333ZBANNNC

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 33nF, -20+80%, 50V, Y5V, 0805

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>F</u> <u>333</u> <u>Z</u> <u>B</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>O</u> <u>C</u> (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11)

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	0805 (inch d	code)	L: 2.0	± 0.1	mm	W:	1.25	± 0.1	mm
				_						
3	Dielectric	Y5V		8	Inner electrode			Ni		
4	Capacitance	<b>33</b> nF			Termina	ation		Cu		
(5)	Capacitance	-20/+80 %			Plating			Sn 100	)%	(Pb Free)
	tolerance			9	Produc	t		Norma	ıl	
6	Rated Voltage	50 V		10	Special			Reserved for future use		future use
7	Thickness	$0.65 \pm 0.1$	mm	11	Packaging			Cardboard Type, 7" reel		

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.05 max.						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	Y5V						
Characterisitcs	(From -30 $^{\circ}\mathrm{C}$ to 85 $^{\circ}\mathrm{C}$ , Capacitance change shoud be within -82~+22%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±30%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5°C, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±20%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change: within ±20%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change : within ±30%	With rated voltage				
Resistance	Tan δ : 0.09 max	40±2°C, 90~95%RH, 500+12/-0hrs				
	IR: 500Mohm or 25Mohm $\cdot \mu$ F					
	Whichever is Smaller					
High Temperature	Capacitance change : within ±30%	With 200% of the rated voltage				
Resistance	Tan δ : 0.09 max	Max. operating temperature				
	IR : 1000Mohm or 50Mohm $\cdot  \mu$ F					
	Whichever is Smaller	1000+48/-0hrs				
Temperature	Capacitance change: within ±20%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C				
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.